L	Hits	Search Text	DB	Time stamp
Number				
-	427	(432/253).CCLS.	USPAT	2004/01/08
				14:56
_	169	(wafer or substrate) and	USPAT	2004/01/08
		((432/253).CCLS.)		15:14
-	223	(432/258).CCLS.	USPAT	2004/01/08
				15:14
-	74	(wafer or substrate) and	USPAT	2004/01/08
		((432/258).CCLS.)		15:25
_	34	((wafer or substrate) and	USPAT	2004/01/08
		((432/258).CCLS.)) not ((wafer or		15:24
		substrate) and ((432/253).CCLS.))		/
-	776	((392/416) or (392/418)).CCLS.	USPAT	2004/01/08
	4.1.1	1	110D3 W	15:25
_	411	(wafer or substrate) and (((392/416) or	USPAT	2004/01/08
	204	(392/418)).CCLS.)	HCDAG	16:16
_	394	((wafer or substrate) and ((($392/416$) or	USPAT	2004/01/08 16:15
		(392/418)).CCLS.)) not ((((wafer or substrate) and ((432/258).CCLS.)) not		10:12
		((wafer or substrate) and		
		((432/253).CCLS.))) or ((wafer or		
		substrate) and ((432/253).CCLS.)))		
_	314	(432/247).CCLS.	USPAT	2004/01/08
	3	(102/21/).0025.		16:17
	20	(wafer or substrate) and	USPAT	2004/01/08
		((432/247).CCLS.)		16:17
_	102	(432/237).CCLS.	USPAT	2004/01/08
				16:17
-	3	(wafer or substrate) and	USPAT	2004/01/08
		((432/237).CCLS.)		16:18
-	388	(432/250).CCLS.	USPAT	2004/01/08
				16:18
-	23	(wafer or substrate) and	USPAT	2004/01/08
		((432/250).CCLS.)		16:21
_	75	(219/443.1).CCLS.	USPAT	2004/01/08
	10	(vertex on substrate) and	USPAT	16:22 2004/01/08
-	10	(wafer or substrate) and ((219/443.1).CCLS.)	\ \sigma_1	16:22
_	120	(219/444.1).CCLS.	USPAT	2004/01/08
	120	(22), 111.1, 0000		16:22
_	112	(wafer or substrate) and	USPAT	2004/01/08
		((219/444.1).CCLS.)		16:32
_	952	(heat\$3 NEAR4 platen) and (wafer or	USPAT	2004/01/08
		substrate) and upper and lower		16:33
-	267	semiconductor and ((heat\$3 NEAR4 platen)	USPAT	2004/01/08
		and (wafer or substrate) and upper and		16:34
		lower)		0004/01/00
-	38	lid and (semiconductor and ((heat\$3 NEAR4	USPAT	2004/01/09
		platen) and (wafer or substrate) and		07:22
		upper and lower))	IIGD D. E.	2004/01/00
-	2285	(lid or cover).ab. and (wafer or	USPAT	2004/01/09
	1 200	semiconductor) and thermal	IICDAT	2004/01/09
-	362	lid.ab. and (wafer or semiconductor) and	USPAT	07:23
L		thermal	L	07.23